

# SSC8211GN2

## P-Channel Enhancement Mode MOSFET

#### > Features

V <sub>DS</sub>	V <sub>GS</sub>	Rds(on)	ID
-16V	±12V	11mΩ@-4V5	-12A
-100		18mΩ@-2V5	-127

#### > Description

This device is produced with high cell density DMOS trench technology, uses advanced trench technology and design to provide excellent RDSON with low gate charge. This device particularly suits low voltage applications such as portable equipment, power management and other battery powered circuits, and low in-line power dissipation are needed in a very small outline surface mount package.

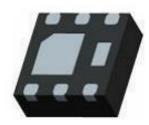
#### > Applications

- Load Switch
- Portable Devices
- DCDC Conversion
- Charging
- Driver for Relay

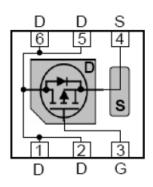
#### > Ordering Information

Device	Package	Shipping		
SSC8211GN2	DFN2X2-6L	3000/Reel		

#### Pin configuration



#### DFN2X2-6L (Bottom View)



Pin Configuration (Top View)





### > Absolute Maximum Ratings ( $T_A=25^{\circ}C$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-to-Source Voltage	V <sub>DSS</sub>	-16	V
Gate-to-Source Voltage	V <sub>GSS</sub>	±12	V
Continuous Drain Current <sup>a</sup>	lo	-12	А
Pulsed Drain Current <sup>b</sup>	ldм	-48	А
Power Dissipation <sup>a</sup>	PD	-2.1	W
Operation junction temperature, Storage temperature range	T <sub>J,</sub> T <sub>STG</sub>	-55 to 150	°C

# > Thermal Resistance Ratings (T<sub>A</sub>=25°C unless otherwise noted)

Symbol	Parameter	Ratings	Unit
R <sub>θJA</sub>	Junction-to-Ambient Thermal Resistance <sup>a</sup>	59	°C/W

Note:

a. The value of R<sub>θJA</sub> is measured with the device mounted on 1 in<sup>2</sup> FR-4 board with 2oz.copper,in a still air environment with T<sub>A</sub>=25 °C. The value in any given application depends on the user is specific board design. The current rating is based on the t≤10s thermal resistance rating.

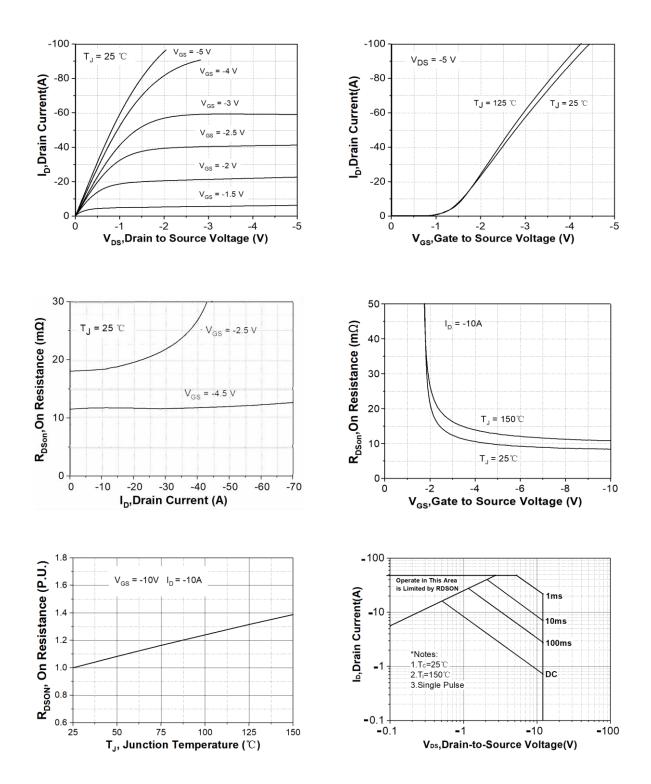
b. Repetitive rating, pulse width limited by junction temperature.

#### > Electrical Characteristics ( $T_A=25^{\circ}C$ unless otherwise noted)

Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Drain-Source Breakdown Voltage	V(BR)DSS	$V_{GS} = 0V, I_D = -250 \mu A$	-16			V	
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}$ , $I_D = -250 uA$	-0.4	-0.75	-1	V	
Drein Source On Registence	5	$V_{GS} = -4.5V, I_D = -7A$		11	18		
Drain-Source On-Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = -2.5V, I <sub>D</sub> = -6A		18	26	mΩ	
Zero Gate Voltage Drain Current	IDSS	$V_{DS} = -12V$ , $V_{GS} = 0V$			-1	μA	
Gate-Source Leak Current	Igss	$V_{GS} = \pm 12V$ , $V_{DS} = 0V$			±100	nA	
Transconductance	GFS	V <sub>DS</sub> = -5V, I <sub>D</sub> = -10A		28		S	
Forward Voltage	V <sub>SD</sub>	V <sub>GS</sub> = 0V, I <sub>S</sub> = -1A		-0.75	-1.3	V	
Input Capacitance	CISS			1745			
Output Capacitance	Coss	$V_{DS} = -8V$ , $V_{GS} = 0V$ ,		480		pF	
Reverse Transfer Capacitance	Crss	f = 1MHz		440			
Turn-on Delay Time	T <sub>D(ON)</sub>	V <sub>GS</sub> = -4.5V, V <sub>DS</sub> = -8V,		13.5			
Rise Time	Tr			45			
Turn-off Delay Time	T <sub>D(OFF)</sub>	$R_{L} = 3\Omega, R_{G} = 1\Omega,$		75		ns	
Fall Time	T <sub>f</sub>	I <sub>D</sub> = -6A		24.5			



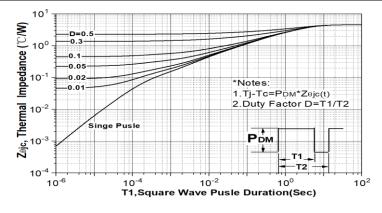
# > Typical Performance Characteristics ( $T_A=25^{\circ}C$ unless otherwise noted)



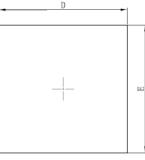
**3** / **6** Analog Future



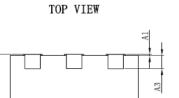
# SSC8211GN2

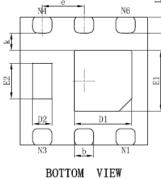


# Package Information









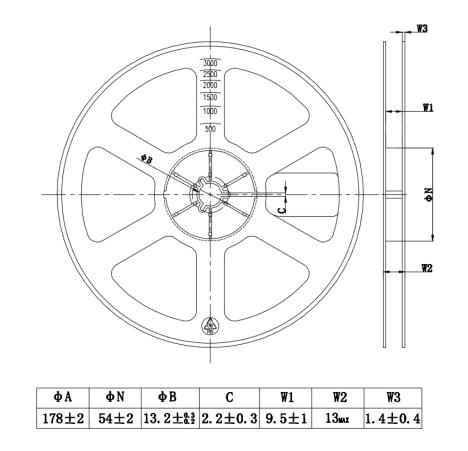
DFN2x2-6L

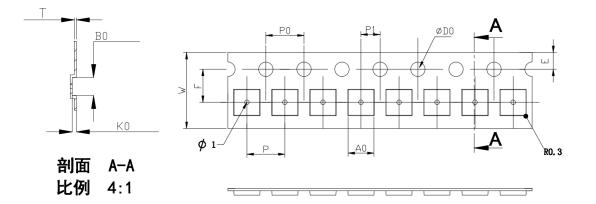
Symbol	Dimensions	Dimensions In Millimeters					
Symbol	Min.	Max.					
Α	0.700	0.800					
A1	0.000	0.050					
A3	0.203	3REF.					
D	1.924	2.076					
E	1.924	2.076					
D1	0.800	1.000					
E1	0.850	1.050					
D2	0.200	0.400					
E2	0.460	0.660					
k	0.200	0.200MIN.					
b	0.250	0.350					
е	0.650	0.650TYP.					
L	0.174	0.326					





# > Tape and Reel





AO	BO	KO	Ρ	PO	E	F	DO	P1	Т	W
2.25±0.05	2.25±0.05	1.15 ±0.05	4.00 ± 0.05	4.00 ± 0.05	1.75 ±0.10	3.50±0.05	1.55 ±0.10	2.00 ± 0.05	0.25±0.05	7.95±0.05

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